

[54] **CIRCUIT MODULE HOUSING**

[56] **References Cited**

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[**] **Term:** 14 Years

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[58] **Field of Search** D13/35, 40, 41, 99; D14/114; 361/331, 342, 346, 380, 381, 383, 390-395, 397, 399, 400, 413, 415-417, 419, 420; 200/302.1, 193; 439/135, 136, 142, 148, 718, 892, 901; 307/116, 118

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[57] **CLAIM**

The ornamental design for a circuit module housing, as shown and described.

DESCRIPTION

FIG. 1 is a top-front-left perspective view of a circuit module housing in accordance with our new design; FIG. 2 is a left-side elevation view thereof; FIG. 3 is a front elevation view thereof; FIG. 4 is a right-side elevation view thereof; FIG. 5 is a back elevation view thereof; FIG. 6 is a top plan view thereof; and FIG. 7 is a bottom plan view thereof.

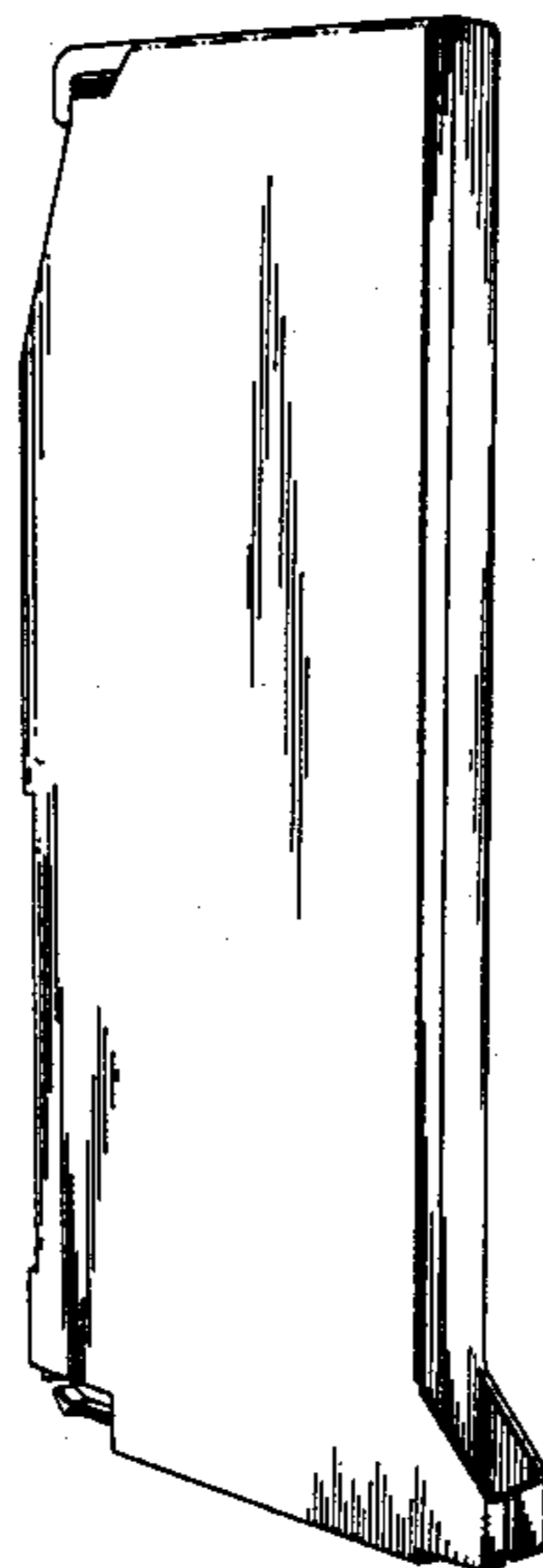


FIG. 1

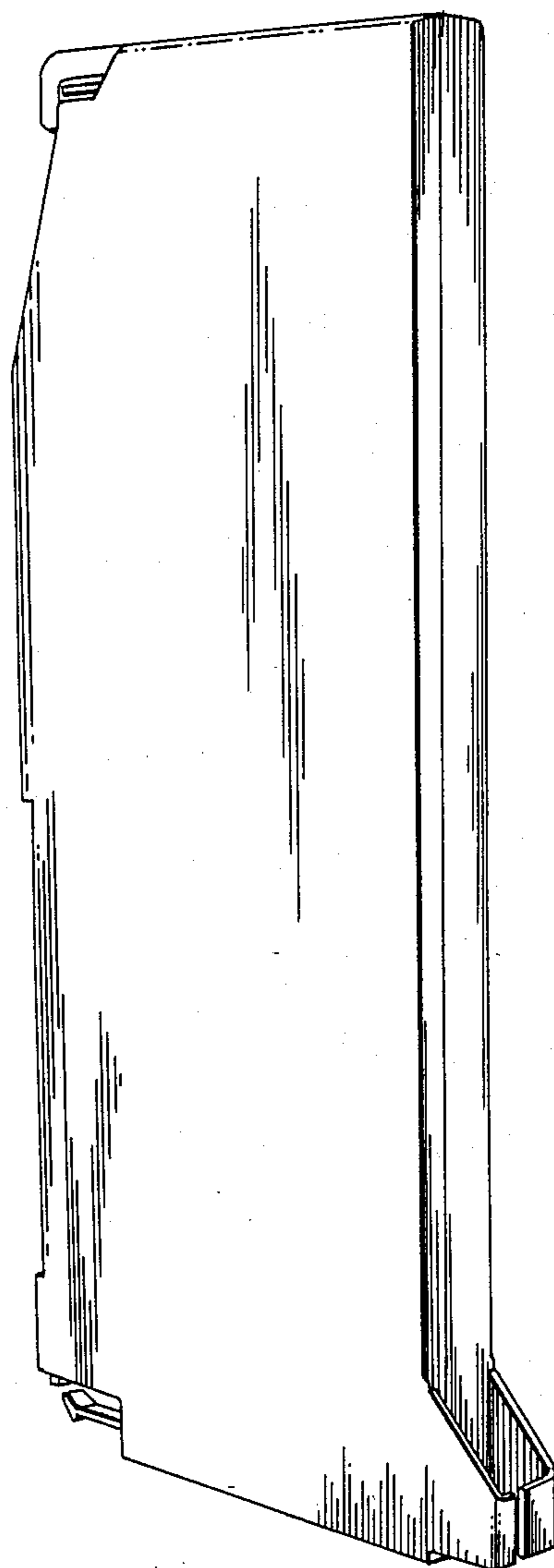


FIG. 2

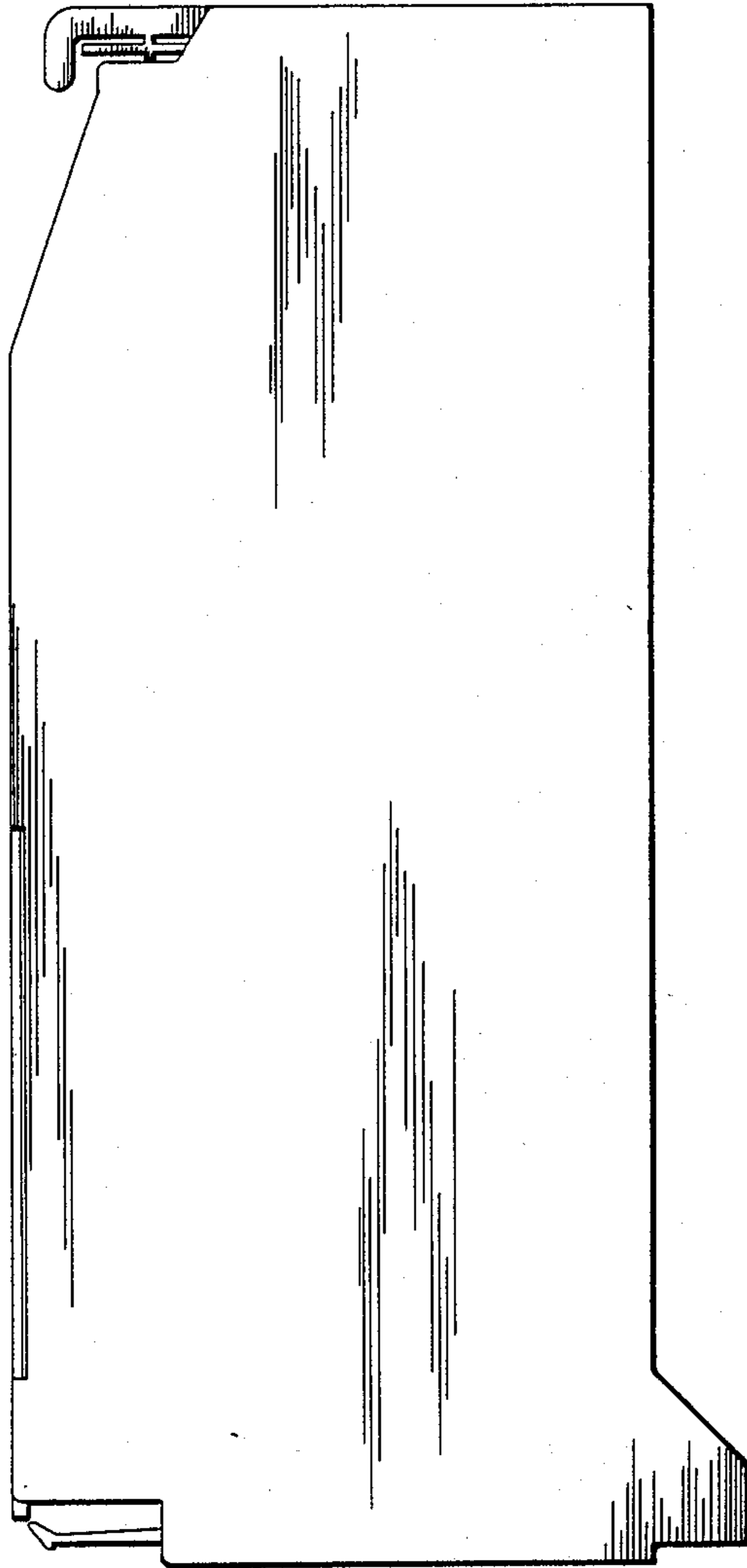


FIG. 3

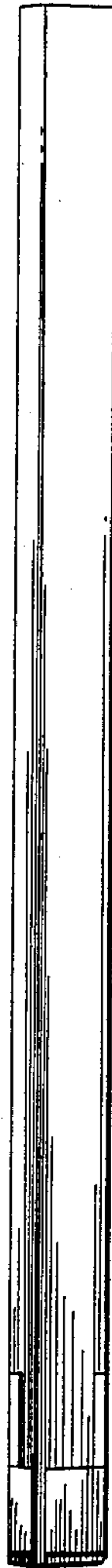


FIG. 4

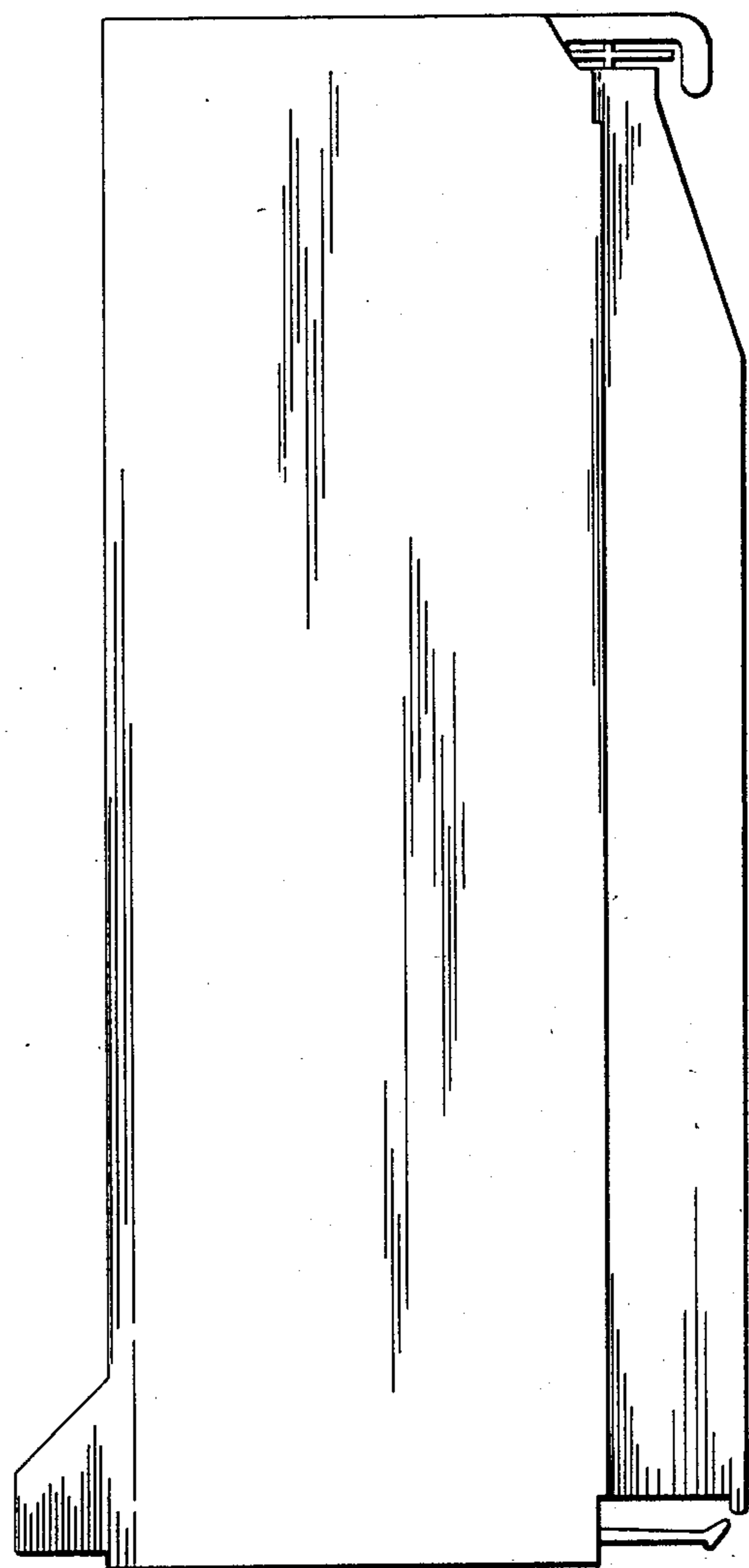


FIG. 5



FIG. 6



FIG. 7

